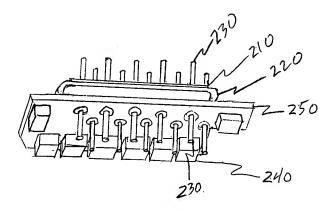
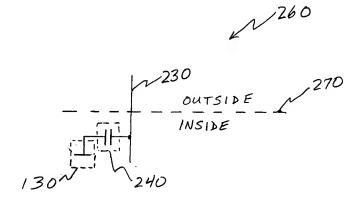


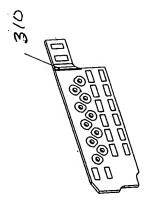
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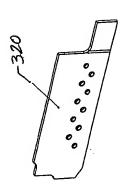


F16.2A



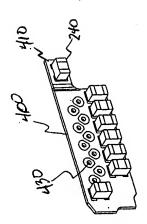
F16. 2B

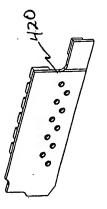


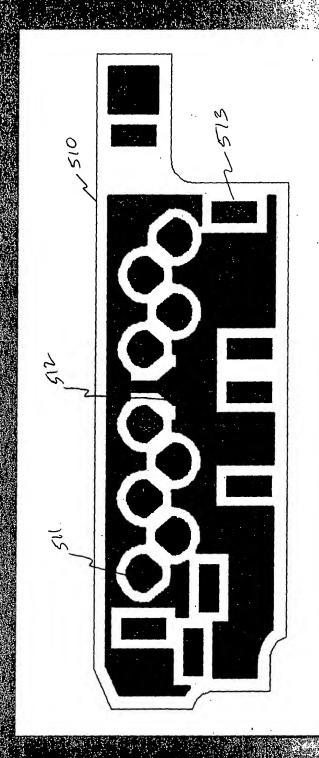


F16.3





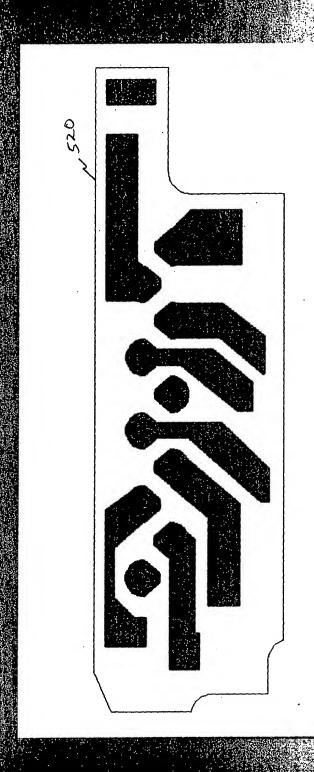




F16.5A

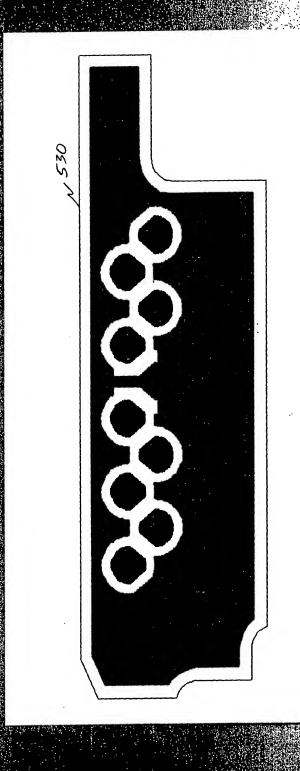
 \mathcal{A}_{j}^{*}





F16 5B

Groumd - Layer 3-



F16.5C

FORMING A HERMETIC SEAL AROUND
A PLURALITY OF I/O PINS THAT
PASS THROUGH A HERMETIC SEAL

FORMING EMI FILTER CIRCUITS
USING DISCRETE CAPACITORS
HOUNTED ON A PRINTED CIRCUIT
SUBSTRATE

Attacking the I/O conductors to
the printed circuit substrate and
the EMI filter circuits

F16.6